



# THE DATASHEET OF TLP521-2XSM





**ISOCOM**  
COMPONENTS

## TLP521, TLP521-2, TLP521-4



### DESCRIPTION

The TLP521, TLP521-2 and TLP521-4 series of optically coupled isolator consist of an infrared light emitting diode and an NPN silicon photo transistor in a space efficient Dual In Line Plastic Package.

### FEATURES

- AC Isolation Voltage 5300V<sub>RMS</sub>
- CTR Selections Available
- Wide Operating Temperature Range  
-30°C to +100°C
- Lead Free and RoHS Compliant
- UL File E91231 Package Code "EE"
- VDE Approval Certificate No. 40028086

### APPLICATIONS

- Computer Terminals
- Industrial System Controllers
- Measuring Instruments
- Signal Transmission between Systems of Different Potentials and Impedances

### ORDER INFORMATION

- Add X after PN for VDE Approval
- Add G after PN for 10mm lead spacing
- Add SM after PN for Surface Mount
- Add SMT&R after PN for Surface Mount Tape & Reel  
(Available for TLP521SM and TLP521-2SM)
- Optional Order Part No. TLP521-1 for TLP521
- Consult Factory for Tape and Reel version of TLP521-4SM

TLP521



TLP521-2



TLP521-4



### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device. Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

#### Input

Forward Current	50mA
Reverse Voltage	6V
Power dissipation	70mW

#### Output

Collector to Emitter Voltage BV <sub>CEO</sub>	55V
Emitter to Collector Voltage BV <sub>ECO</sub>	6V
Collector Current	50mA
Power Dissipation	150mW

#### Total Package

Isolation Voltage	5300V <sub>RMS</sub>
Total Power Dissipation	200mW
Operating Temperature	-30 to 100 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

#### ISOCOM COMPONENTS 2004 LTD

Unit 25B, Park View Road West, Park View Industrial Estate  
Hartlepool, Cleveland, TS25 1PE, United Kingdom  
Tel : +44 (0)1429 863 609 Fax : +44 (0)1429 863 581  
e-mail : sales@isocom.co.uk  
<http://www.isocom.com>

#### ISOCOM COMPONENTS ASIA LTD

Hong Kong Office  
Block A, 8/F, Wah Hing Industrial Mansion  
36 Tai Yau Street, San Po Kong, Kowloon, Hong Kong  
Tel : +852 2995 9217 Fax : +852 8161 6292  
e-mail : sales@isocom.com.hk





**TLP521, TLP521-2, TLP521-4**

**ELECTRICAL CHARACTERISTICS (Ambient Temperature = 25°C unless otherwise specified)**

**COUPLED**

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Current Transfer Ratio	CTR	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$	50		600	%
		Optional CTR Grades				
		GR	100		300	
		BL	200		600	
		GB	100		600	
		GB ( $I_F = 1\text{mA}, V_{CE} = 0.4\text{V}$ )	30			
Collector—Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F = 8\text{mA}, I_C = 2.4\text{mA}$ GB ( $I_F = 1\text{mA}, I_C = 0.2\text{mA}$ )			0.4 0.4	V
Output Rise Time	$t_r$	$V_{CE} = 2\text{V},$ $I_C = 2\text{mA},$ $R_L = 100\Omega$		4		$\mu\text{s}$
Output Fall Time	$t_f$			3		
Turn-on Time	$t_{on}$			3		
Turn-off Time	$t_{off}$			3		
Turn-on Time	$t_{ON}$	$V_{CC} = 5\text{V},$ $I_F = 16\text{mA},$ $R_L = 1.9\text{k}\Omega$		2		$\mu\text{s}$
Turn-off Time	$t_{OFF}$			25		

**ISOLATION**

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Input to Output Isolation Voltage	$V_{ISO}$	AC 1 minute, RH = 40 to 60% Note 1	5300			$V_{RMS}$
Input to Output Isolation Resistance	$R_{ISO}$	$V_{IO} = 500\text{V}$ Note 1	$5 \times 10^{10}$			$\Omega$

Note 1 : Measure with input leads shorted together and output leads shorted together.



## TLP521, TLP521-2, TLP521-4



Fig 1 Forward Current vs  $T_A$



Fig 2 Collector Power Dissipation vs  $T_A$

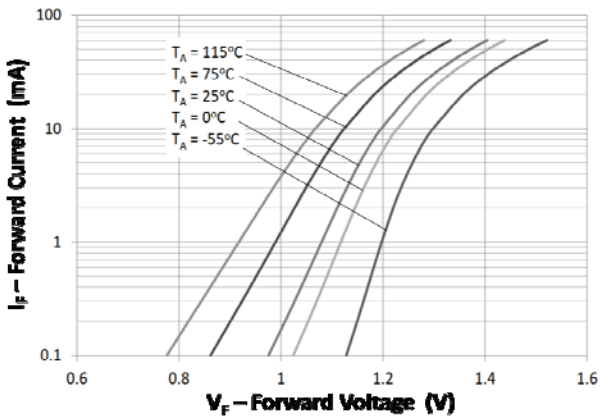


Fig 3 Forward Current vs Forward Voltage



Fig 4 Collector Current vs Collector-Emitter Voltage

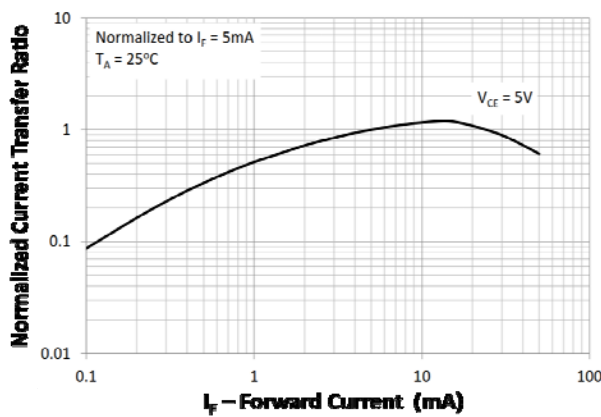


Fig 5 Normalized Current Transfer Ratio vs Forward Current



Fig 6 Normalized Current Transfer Ratio vs Ambient Temperature



## TLP521, TLP521-2, TLP521-4

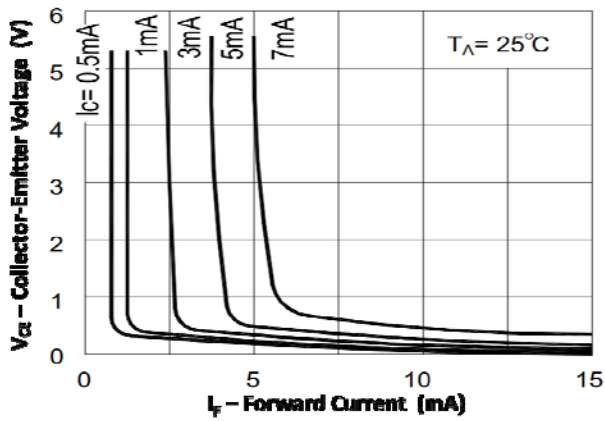


Fig 7 Collector-Emitter Voltage vs Forward Current

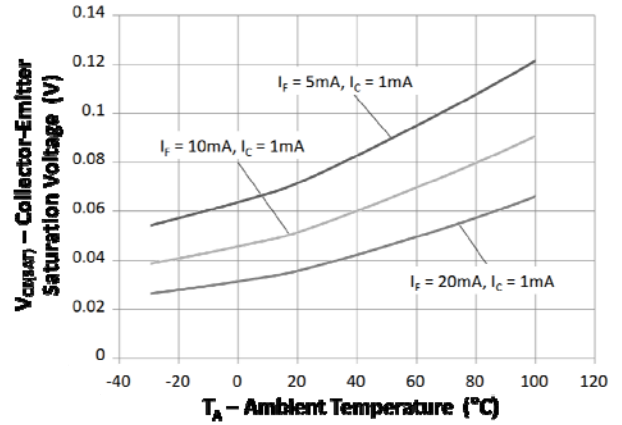


Fig 8 Collector-Emitter Voltage vs Ambient Temperature



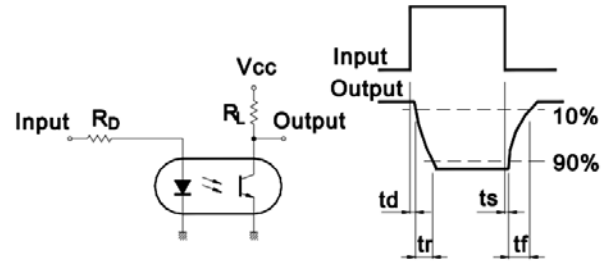
Fig 9 Collector Dark Current vs Ambient Temperature



## TLP521, TLP521-2, TLP521-4



Fig 7 Response Time vs Load Resistance



Response Time Test Circuit

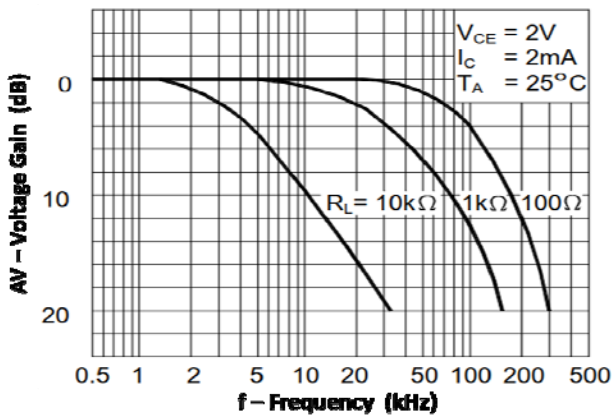


Fig 9 Frequency Response



Frequency Response Test Circuit







## TLP521, TLP521-2, TLP521-4

### ORDER INFORMATION

TLP521X, TLP521-1X (UL and VDE Approvals)			
After PN	PN	Description	Packing quantity
None	TLP521X, TLP521-1X TLP521XGR, TLP521-1XGR TLP521XBL, TLP521-1XBL, TLP521XGB, TLP521-1XGB	Standard DIP4	100 pcs per tube
G	TLP521XG, TLP521-1XG, TLP521XGRG, TLP521-1XGRG, TLP521XBLG, TLP521-1XBLG TLP521XGBG, TLP521-1XGBG	10mm Lead Spacing	100 pcs per tube
SM	TLP521XSM, TLP521-1XSM, TLP521XGRSM, TLP521-1XGRSM, TLP521XBLSM, TLP521-1XBLSM, TLP521XGBSM, TLP521-1XGBSM	Surface Mount	100 pcs per tube
SMT&R	TLP521XSMT&R, TLP521-1XSMT&R TLP521XGRSMT&R, TLP521-1XGRSMT&R, TLP521XBLSMT&R, TLP521-1XBLSMT&R, TLP521XGBSMT&R, TLP521-1XGBSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

Note : Optional Order Part No. TLP521-1 for TLP521.



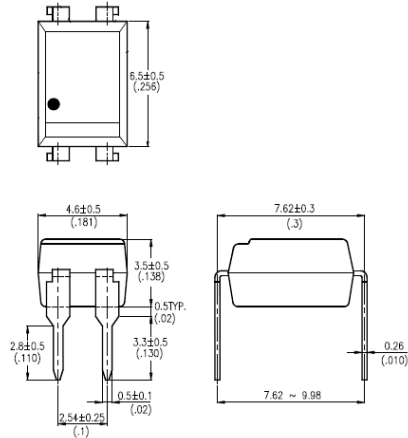


## TLP521, TLP521-2, TLP521-4

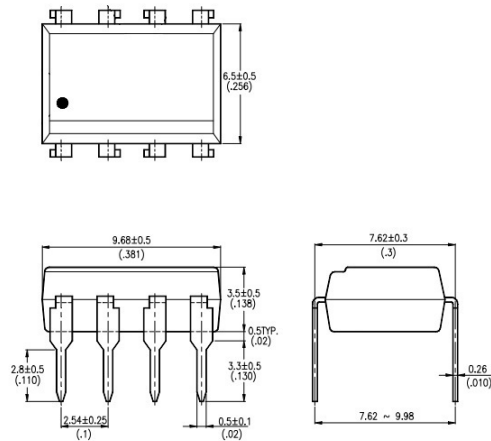
### PACKAGE DIMENSIONS in mm (inch)

#### DIP

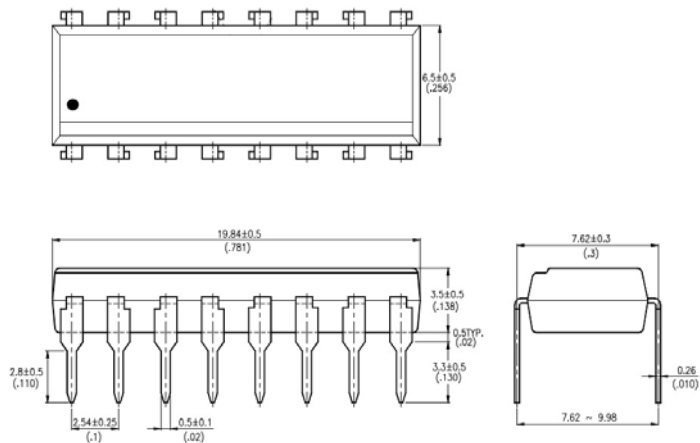
**TLP521**



**TLP521-2**



**TLP521-4**



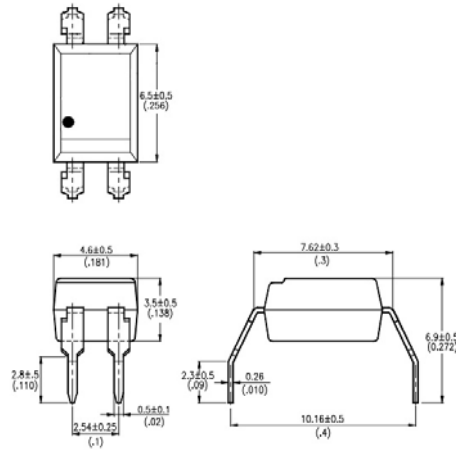


## TLP521, TLP521-2, TLP521-4

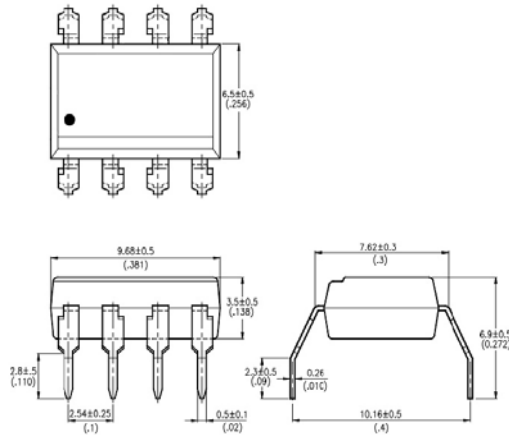
### PACKAGE DIMENSIONS in mm (inch)

#### G Form

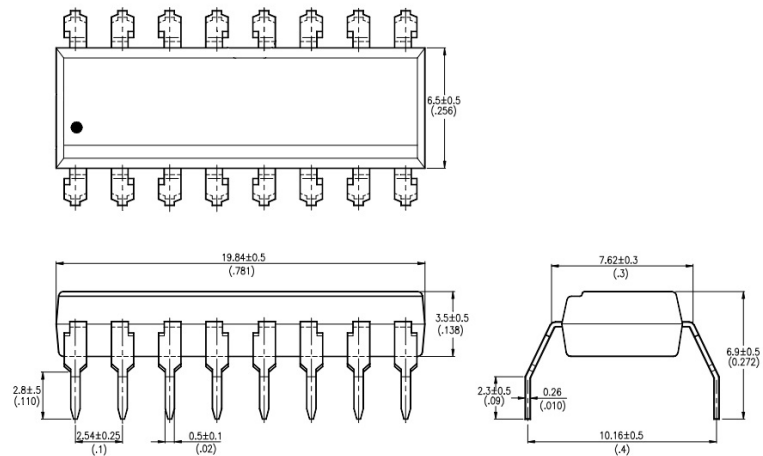
**TLP521G**



**TLP521-2G**



**TLP521-4G**



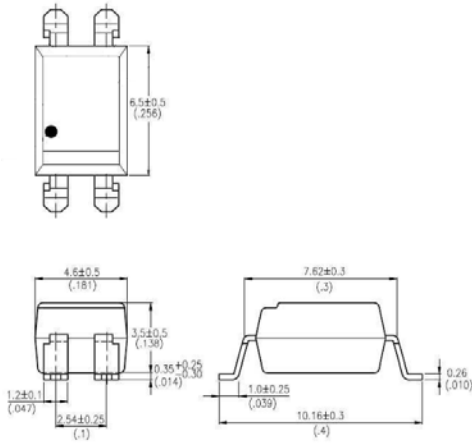


## TLP521, TLP521-2, TLP521-4

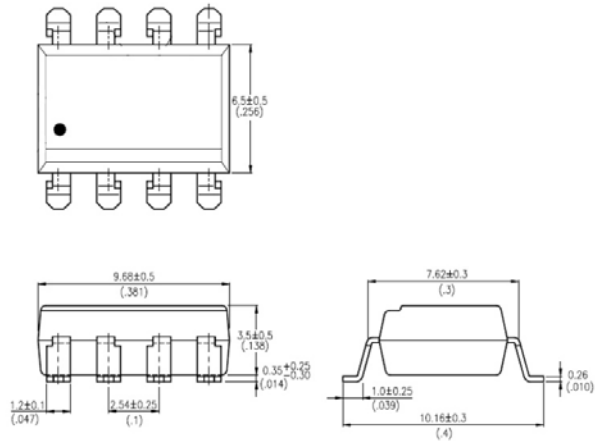
### PACKAGE DIMENSIONS in mm (inch)

#### SMD

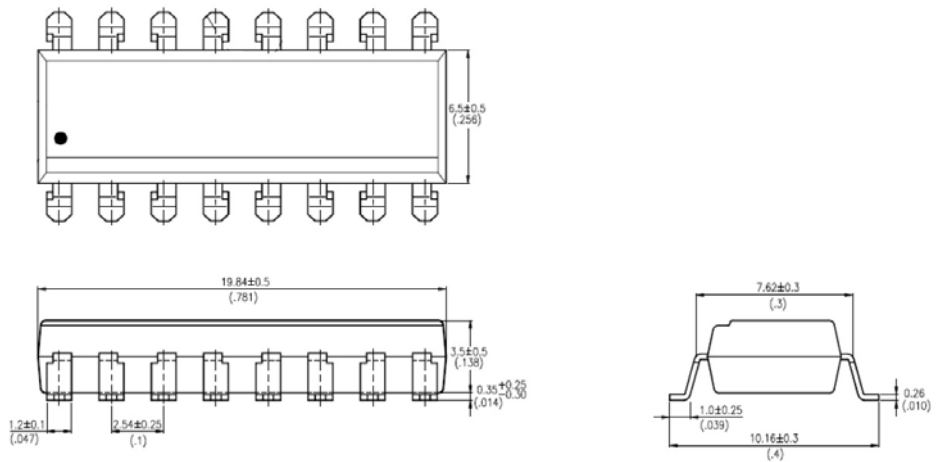
**TLP521SM**



**TLP521-2SM**



**TLP521-4SM**





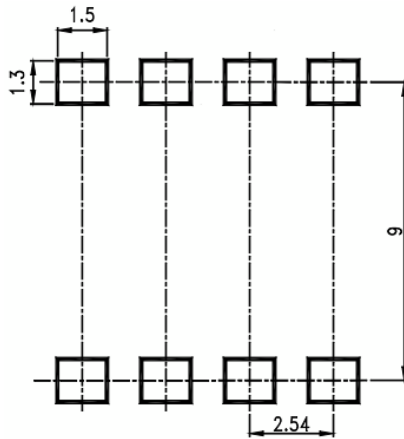
## TLP521, TLP521-2, TLP521-4

### RECOMMENDED PAD LAYOUT FOR SMD (mm)

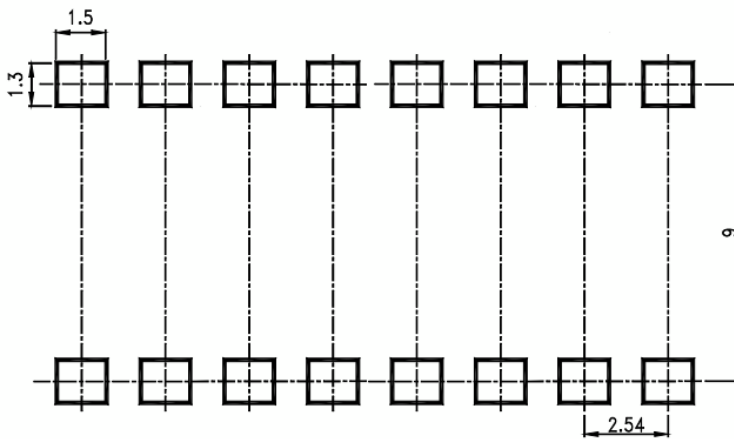
**TLP521SM**



**TLP521-2SM**



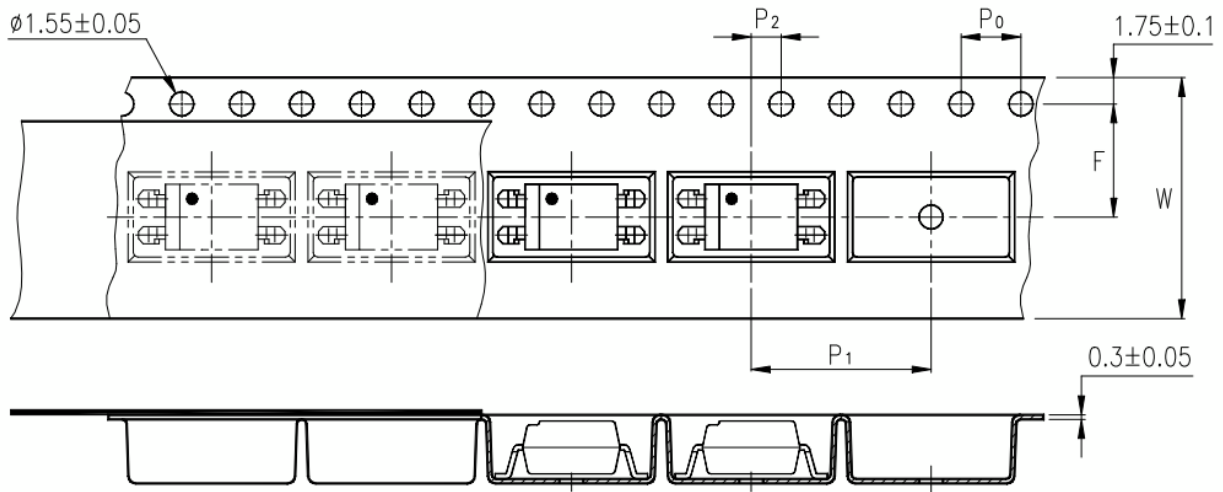
**TLP521-4SM**



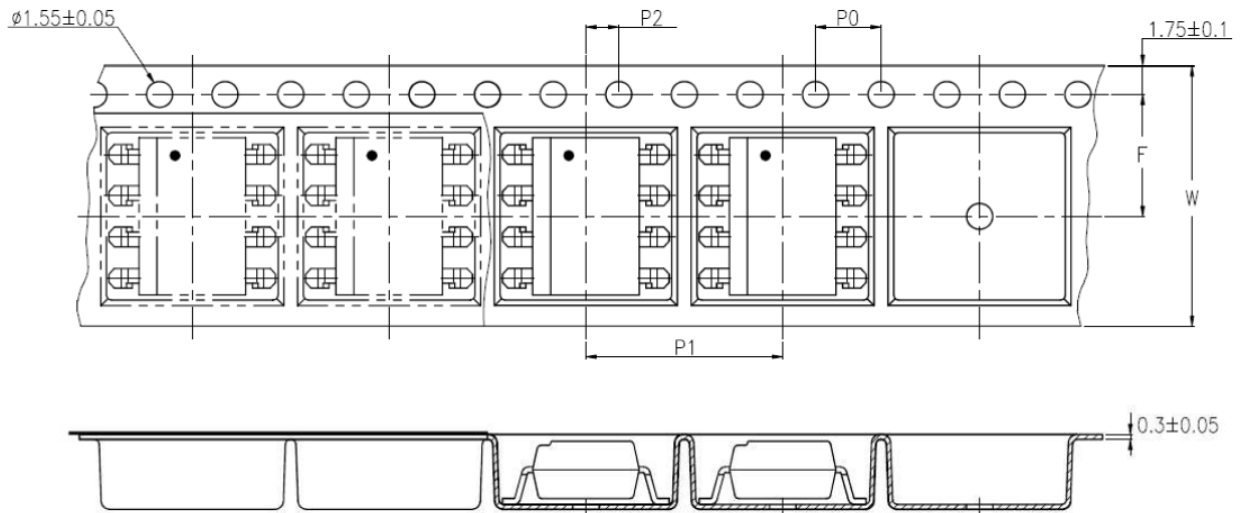


**TLP521, TLP521-2, TLP521-4**

**TAPE AND REEL PACKAGING**



**TLP521SMT&R**



**TLP521-2SMT&R**

Description	Symbol	Dimensions in mm ( inches )
Tape wide	W	$16 \pm 0.3$ ( .63 )
Pitch of sprocket holes	$P_0$	$4 \pm 0.1$ ( .15 )
Distance of compartment	F	$7.5 \pm 0.1$ ( .295 )
Distance of compartment to compartment	$P_2$	$2 \pm 0.1$ ( .079 )
Distance of compartment to compartment	$P_1$	$12 \pm 0.1$ ( .472 )



**TLP521, TLP521-2, TLP521-4**

**IR REFLOW SOLDERING TEMPERATURE PROFILE FOR SMD  
(One Time Reflow Soldering is Recommended)**




Profile Details	Conditions
<b>Preheat</b> - Min Temperature ( $T_{SMIN}$ ) - Max Temperature ( $T_{SMAX}$ ) - Time $T_{SMIN}$ to $T_{SMAX}$ ( $t_s$ )	150°C 200°C 60s - 120s
<b>Soldering Zone</b> - Peak Temperature ( $T_P$ ) - Time at Peak Temperature - Liquidous Temperature ( $T_L$ ) - Time within 5°C of Actual Peak Temperature ( $T_P - 5^\circ C$ ) - Time maintained above $T_L$ ( $t_L$ ) - Ramp Up Rate ( $T_L$ to $T_P$ ) - Ramp Down Rate ( $T_P$ to $T_L$ )	260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate ( $T_{smax}$ to $T_P$ )	3°C/s max
Time 25°C to Peak Temperature	8 minutes max





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